IEEE 802.3 Ethernet Working Group
Liaison Communication

Source:	IEEE 802.3 Working Group[1]	
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Subject: Liaison to IEEE P370 Electrical Characterization of High Speed Interconnect

Approval: Agreed to at IEEE 802.3 interim meeting, Salt Lake City, UT, USA, 23rd May 2019

Dear Mr Ye,

Thank you for sharing the D5.0 draft of IEEE P370 Electrical Characterization of Printed Circuit Board and Related Interconnects at Frequencies up to 50 GHz. Please find attached to this letter a copy of the IEEE P802.3ch D2.0 Draft Standard for Ethernet Amendment: Physical Layer Specifications and Management Parameters for Greater Than 1 Gb/s Automotive Ethernet.

The IEEE P802.3ck 100 Gb/s, 200 Gb/s, and 400 Gb/s Electrical Interfaces Based on 100 Gb/s Signaling project does not yet have a draft. We will send you a copy of a draft in the future when it becomes available.

We look forward to working with the IEEE P370 Working Group in the future.

Sincerely,
David Law
Chair, IEEE 802.3 Ethernet Working Group

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[1] This document solely represents the views of the IEEE 802.3 Working Group, and does not necessarily represent a position of the IEEE, the IEEE Standards Association, or IEEE 802.